


APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	PROBE TIP DESIGN APPLIED IN A FLIP CHIP PACKAGING PROCESS		
Application Type : regular, utility Attorney Docket Number : NAUP0520USA			
Correspondence address: Customer Number: 027765			
			
Inventors Information:			
<u>Inventor 1:</u>			
Applicant Authority Type:	Inventor		
Citizenship:	TW		
Given Name:	Hung-Min		
Family Name:	Liu		
Residence:			
City of Residence:	Hsin-Chu City		
Country of Residence:	TW		
Address-1 of Mailing Address:	4F, No. 30, Lane 81, Ta-Hsueh Rd.		
Address-2 of Mailing Address:			
City of Mailing Address:	Hsin-Chu City		
State of Mailing Address:			
Postal Code of Mailing Address:			
Country of Mailing Address:	TW		
Phone:			
Fax:			
E-mail:			
<u>Inventor 2:</u>			
Applicant Authority Type:	Inventor		
Citizenship:	TW		
Given Name:	Kow-Bao		
Family Name:	Chen		
Residence:			
City of Residence:	Hsin-Chu City		

Country of Residence: TW
Address-1 of Mailing Address: No. 11, Lane 156, Nan-Ya St.
Address-2 of Mailing Address:
City of Mailing Address: Hsin-Chu City
State of Mailing Address:
Postal Code of Mailing Address:
Country of Mailing Address: TW
Phone:
Fax:
E-mail:

Attorney Information:

practitioner(s) at Customer Number:

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.